



## Product Bulletin

Better Chemistry. **Better Business.**

**Microetch 6075**

**Product Code: 2703003**  
**Revised Date: 07/19/2006**

### Microetch 6075

**Microetch 6075** is a powdered material, which is simply mixed with DI water and sulfuric acid to make up the operating solution. The **Microetch 6075** solution is used in printed circuit processes for deoxidizing copper and for producing a mild etch on the surface prior to electroless plating.

**Microetch 6075** provides a clean, uniformly etched copper surface and prepares the printed circuit boards for activation and electroless plating. It is designed as a substitute for ammonium persulfate and other proprietary products containing ammonium compounds. It is simple to make up and requires no elaborate control procedures.

### MAKE-UP

1. DI water amount necessary to reach operating volume
2. **Microetch 6075** 8-12 oz/gal
3. Sulfuric acid 66 be' 1/2-1% by volume

To make up the operating solution, fill 3/4 of the tank with DI water. Add 8-12 oz/gal of the **Microetch 6075** powder. Add 1/2-1% by volume sulfuric acid. Bring the solution to final volume with DI water.

### OPERATING CONDITIONS

Temperature: 70-85F.  
Immersion time: as required.  
Concentration: 8-12 oz/gal (see control section)

Additional recommendations can be made on a plant-by-plant basis depending upon specific requirements.

### OPERATION

After normal cleaning and rinsing, the printed circuit boards are simply immersed in the **Microetch 6075** operating solution for the necessary period of time. Longer immersion times will be necessary when the solution is operated at the lower end of the temperature range. Increased temperatures will reduce the time. Do not operate the solution above the recommended limit.



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### EQUIPMENT

PVC, polyethylene, fiberglass, or rubber lined tanks.

### SOLUTION MAINTENANCE

The operating solution should be maintained at a concentration of 8-12 oz/gal for daily usage. Specific timetables for additions will be suggested based on total work load per shift.

### CONTROL PROCEDURES

#### **DETERMINING CONCENTRATIONS OF MICROETCH 6075**

#### **Reagents required:**

- A. 0.1N potassium permanganate (KMNO<sub>4</sub>)
- B. 0.2N ferrous ammonium sulfate (FESO<sub>4</sub> (NH<sub>4</sub>) SO<sub>4</sub> - 6 H<sub>2</sub>O)  
preparing ferrous ammonium sulfate solution  
78.5 gms ferrous ammonium sulfate  
5.0 mls concentrated sulfuric acid  
distilled water-make one liter
- C. 25% (vol) sulfuric acid solution  
slowly add 100 mls sulfuric acid to 600 mls distilled water

#### **Procedure:**

1. Pipette a 1 ml sample into a 250 ml erlenmeyer flask.
2. Add 25 mls of DI water.
3. Pipette 10 mls of 0.2N ferrous ammonium sulfate into the flask and wait one minute.
4. Pipette 5 mls of 25% H<sub>2</sub>SO<sub>4</sub> into the flask.
5. Titrate with 0.1N KMNO<sub>4</sub> to a light pink endpoint.
6. Record the number of mls of KMNO<sub>4</sub> used as "a" mls.
7. Perform the same analysis on a blank solution. (i.e. run through steps 2-5)
8. Record number of mls of KMNO<sub>4</sub> used as "b" mls.

### CALCULATION

$$(b-a) (1.65) = \text{oz/gal Microetch 6075}$$



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### SULFURIC ACID CONCENTRATION

1. Pipette 10 mls of working solution into a 250 ml Erlenmeyer flask and add about 100 ml DI water.
2. Add 2-3 drops of methyl orange indicator
3. Titrate with a 1.0N NAOH solution to a yellow-green endpoint.
4. Record mls 1.0N NAOH used.

$$\% \text{ (vol) sulfuric acid} = \text{mls 1.0N NAOH used} \times 0.28$$

### WASTE TREATMENT

Spent solutions must be adjusted to a ph of 7 to 10 in order to remove the copper metal prior to disposal. Dilute sodium hydroxide (caustic soda) solutions are recommended for this procedure. Consult local authorities for specific regulations concerning discarding of spent material.

### CAUTION

Use only sulfuric acid when making up the operating solution. Use of hydrochloric acid will liberate chlorine gas; nitric acid will liberate nitric oxide and nitrogen dioxide gas.

**Microetch 6075** and its operating solution are acidic and oxidizing in nature. Avoid contact with reducing agents, alkalis, and solvents, or organic materials such as paper, wood, cloth or sulfur. Avoid all acids other than sulfuric.

Wear rubber gloves, aprons, and safety glasses when handling **Microetch 6075** and the working solution. Do not inhale the dust of the **Microetch 6075** powder. Wear respirator when handling. In case of contact with the skin or eyes, flush with cold water for 15 minutes and obtain medical attention.

### WARRANTY

THE QUALITY OF THIS PRODUCT IS GUARANTEED ON SHIPMENT FROM OUR PLANT. IF THE USE RECOMMENDATIONS ARE FOLLOWED, DESIRED RESULTS WILL BE OBTAINED. SINCE THE USE OF OUR PRODUCTS IS BEYOND OUR CONTROL, NO GUARANTEE EXPRESSED OR IMPLIED IS MADE AS TO THE EFFECTS OF SUCH USE, OR THE RESULTS TO BE OBTAINED.